

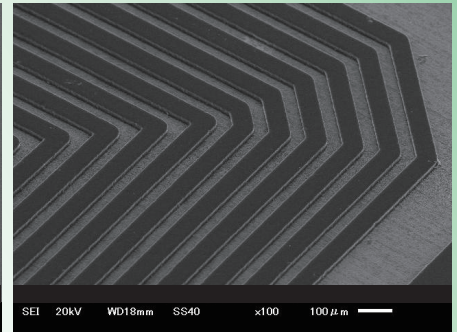
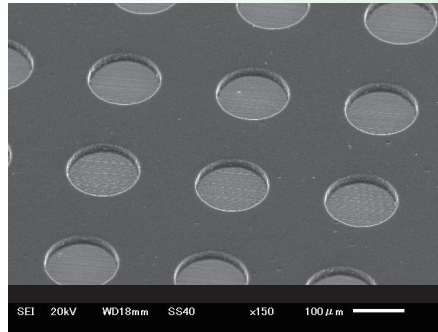
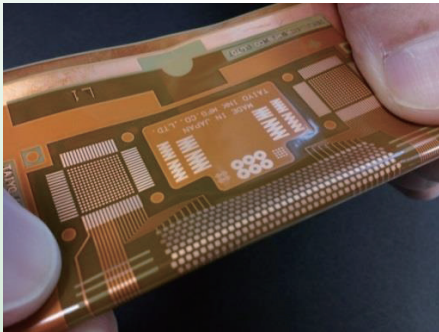


感光性カバーレイフィルム

Photo Imageable Cover Lay Film

特長 Features

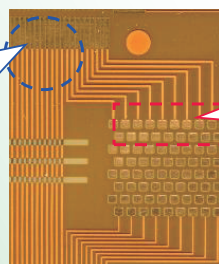
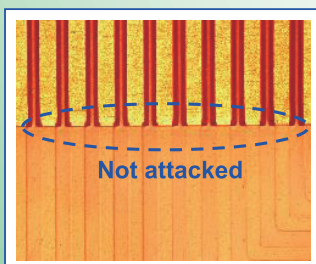
- 高解像性と高屈曲性の両立を実現した感光性ポリイミドフィルム
Photo imageable polyimide film with coexistence of high resolution and high bendability
- 現行のプリント配線板製造ラインへの適用を実現
Applicable to current PWB photolithography process
- 優れた耐熱性と絶縁信頼性と難燃性(VTM-0相当)を実現
Excellent heat resistance, insulation reliability and flame resistance (VTM-0 equivalent)



特性 Properties

| Item | Condition | Result |
|-----------------------|--|----------------|
| Pencil hardness | JIS 5600 | 4H |
| Acid resistance | 10 vol% H ₂ SO ₄ aq. 25 deg.C × 20 min | Pass |
| Alkaline resistance | 10 wt% NaOHaq. 25 deg.C × 20 min | Pass |
| Heat resistance | Solder floating 288 deg.C × 10 sec | Pass |
| Au plating resistance | ENIG Ni:4 um Au:0.1um | Pass |
| Tg | TMA | 167 deg.C |
| Bendability | 180 deg. folding | above 20 times |

ENIG resistance [Ni: 4.0um Au: 0.1um]



Solder heat resistance [288deg.C × 10sec × 2 times]

